



## Material Content Data Sheet



<b>Sales Product Name</b>		BSO211P H		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA000734806						
<b>Package</b>		PG-DSO-8-40		<b>Weight*</b>		82.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.109	1.35	1.35	13462	13462
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		119	
	non noble metal	zinc	7440-66-6	0.039	0.05		477	
	non noble metal	iron	7439-89-6	0.785	0.95		9530	
	non noble metal	copper	7440-50-8	31.880	38.70	39.71	386965	397091
wire	non noble metal	copper	7440-50-8	0.158	0.19	0.19	1923	1923
encapsulation	organic material	carbon black	1333-86-4	0.235	0.28		2850	
	plastics	epoxy resin	-	7.280	8.84		88363	
	inorganic material	silicondioxide	60676-86-0	39.452	47.88	57.00	478871	570084
leadfinish	non noble metal	tin	7440-31-5	0.814	0.99	0.99	9878	9878
plating	noble metal	silver	7440-22-4	0.063	0.08	0.08	763	763
glue	plastics	epoxy resin	-	0.084	0.10		1020	
	noble metal	silver	7440-22-4	0.476	0.58	0.68	5779	6799
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com